

3A Avg.

20 Volts

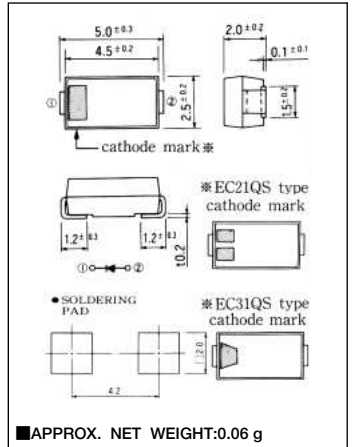
SBD

EC30LB02

■最大定格 Maximum Ratings

Item	Symbol	Conditions	Unit
くり返しピーク逆電圧 Repetitive Peak Reverse Voltage	$V_{RRM}$	20	V
直流通電 Direct Forward Current	$I_{DC}$	$T_a=102^{\circ}\text{C}^*$ T:Lead Temperature	3.0 A
		$T_a=28^{\circ}\text{C}^*$	2.8 A
サージ順電流 Surge Forward Current	$I_{FSM}$	80 50Hz正弦半波, 1サイクル, 非くり返し 50Hz Half Sine Wave, 1cycle, Non-repetitive	A
動作接合温度範囲 Operating Junction Temperature Range	$T_{jw}$	-40~+125	$^{\circ}\text{C}$
保存温度範囲 Storage Temperature Range	$T_{stg}$	-40~+125	$^{\circ}\text{C}$

■OUTLINE DRAWING(mm)



■電氣的・熱的特性 Electrical/Thermal Characteristics

Item	Symbol	Conditions	Min.	Typ.	Max.	Unit
ピーク逆電流 Peak Reverse Current	$I_{RM}$	$T_j=25^{\circ}\text{C}$ , $V_{RM}=V_{RRM}$	—	—	1	mA
ピーク順電圧 Peak Forward Voltage	$V_{FM}$	$T_j=25^{\circ}\text{C}$ , $I_{FM}=3.0\text{A}$	—	—	0.41	V
熱抵抗 Thermal Resistance	$R_{th(j-a)}$	接合部・周囲間 Junction to Ambient	—	—	108	$^{\circ}\text{C}/\text{W}$
	$R_{th(j-l)}$	接合部・リード間 Junction to Lead	—	—	23	$^{\circ}\text{C}/\text{W}$

\*プリント基板実装 / Alumina Substrate Mounted (Soldering Land=2×2mm, Both Sides)

■定格・特性曲線

